場隔離 (field isolation) 431

場電晶體 (field transistor) 147-148

復合 (recombination) 20-23, 45, 49, 53, 57-60, 95, 456

復合雜訊 (generation-recombination noise) 456

提升源/汲極 (raised S&D) 248, 265

揮發性 (volatile) 352, 355, 369, 376, 379, 386

散射 (scattering) 63, 149-151, 228, 230, 232, 237-238, 268, 279-280, 453

散彈雜訊 (shot noise) 456

晶片級封裝 CSP (Chip Scale Packaging) 389

晶格散射 (lattice scattering) 63, 151, 232

晶粒 (die 或 chip) 207, 258, 277, 414

晶圓廠 (Foundry) 196, 258, 459, 461

智慧卡 (smart card) 377,406

氮退火 (nitrogen anneal) 239

游離 (ionize) 11-12, 17, 24, 62-63, 65-66

渠道優先 (trench first) 253

測試鍵 (test key 或 test structure) 414, 428-432, 434-441, 443-444, 448, 466-468

短通道 (short-channel) 71, 122, 136, 138, 149, 158-162, 164-175, 177, 179, 223, 230-232, 237-239, 241, 243-246, 248, 255, 258, 262, 264, 283, 331-332, 367, 422-423, 461

短通道效應 (short channel effects) 122, 158, 160, 169, 171, 173, 179, 223, 230-232, 237-239, 241, 243, 246, 262, 264, 367, 423, 461

硬烤 (hard bake) 190-191

等向性(isotropic) 187, 192-193, 203

等效氧化層厚度 (equivalent oxide thickness, EOT) 275, 278

絕緣體 (insulator) 3, 76, 78, 89, 122, 132, 355

虚置圖案 (dummy patterns) 226

費米分布函數 (Fermi distribution function) 2,4

費米位能 (Fermi potential) 418

費米能階 (Fermi level) 4-7, 11-13, 24, 30, 32-33, 38, 77-79, 81, 97-98, 140, 280-283

費米能階固定 (Fermi level pinning) 280-283

軸纜數據終端系統(Cable Modem Termination System; CMTS) 398

納 (sodium) 102, 207, 213

開狀態電流 (on-state current 或 on current) 142, 152

開關 (switch) 122, 141-142, 221, 239, 249, 258, 300-301, 304-305, 405, 415-416, 420, 435, 444, 466

間隔離 (well-to-well isolation) 229-230, 427, 429-430, 467